



THE DATASHEET OF IRFR9024PBF



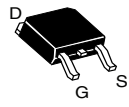
Power MOSFET



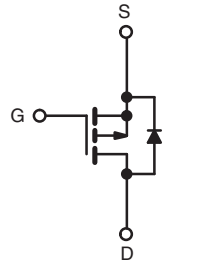
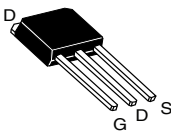
RoHS
COMPLIANT
HALOGEN
FREE
Available

PRODUCT SUMMARY		
V_{DS} (V)	- 60	
$R_{DS(on)}$ (Ω)	$V_{GS} = -10$ V	0.28
Q_g (Max.) (nC)	19	
Q_{gs} (nC)	5.4	
Q_{gd} (nC)	11	
Configuration	Single	

DPAK
(TO-252)



IPAK
(TO-251)



P-Channel MOSFET

FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Surface Mount (IRFR9024, SiHFR9024)
- Straight Lead (IRFU9024, SiHFU9024)
- Available in Tape and Reel
- P-Channel
- Fast Switching
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The DPAK is designed for surface mounting using vapor phase, infrared, or wave soldering techniques. The straight lead version (IRFU, SiHFU series) is for through-hole mounting applications. Power dissipation levels up to 1.5 W are possible in typical surface mount applications.

ORDERING INFORMATION					
Package	DPAK (TO-252)	DPAK (TO-252)	DPAK (TO-252)	DPAK (TO-252)	IPAK (TO-251)
Lead (Pb)-free and Halogen-free	SiHFR9024-GE3	SiHFR9024TR-GE3 ^a	SiHFR9024TRL-GE3 ^a	SiHFR9024TRR-GE3 ^a	SiHFU9024-GE3
Lead (Pb)-free	IRFR9024PbF	IRFR9024TRPbF ^a	IRFR9024TRLPbF ^a	IRFR9024TRRPbF ^a	IRFU9024PbF
	SiHFR9024-E3	SiHFR9024T-E3 ^a	SiHFR9024TL-E3 ^a	SiHFR9024TR-E3 ^a	SiHFU9024-E3

Note

- a. See device orientation.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	- 60	V	
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current	V_{GS} at - 10 V	$T_C = 25$ °C	- 8.8	A
		$T_C = 100$ °C	- 5.6	
Pulsed Drain Current ^a	I_{DM}	- 35	W/°C	
Linear Derating Factor		0.33		
Linear Derating Factor (PCB Mount) ^e		0.020		
Single Pulse Avalanche Energy ^b	E_{AS}	300	mJ	
Repetitive Avalanche Current ^a	I_{AR}	- 8.8	A	
Repetitive Avalanche Energy ^a	E_{AR}	5.0	mJ	
Maximum Power Dissipation	P_D	$T_C = 25$ °C	42	W
Maximum Power Dissipation (PCB Mount) ^e		$T_A = 25$ °C	2.5	
Peak Diode Recovery dV/dt ^c	dV/dt	- 4.5	V/ns	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	°C	
Soldering Recommendations (Peak Temperature) ^d	for 10 s	260		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
 b. $V_{DD} = -25$ V, starting $T_J = 25$ °C, $L = 4.5$ mH, $R_g = 25$ Ω , $I_{AS} = -8.8$ A (see fig. 12).
 c. $I_{SD} \leq -11$ A, $dI/dt \leq 140$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
 d. 1.6 mm from case.
 e. When mounted on 1" square PCB (FR-4 or G-10 material).



THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R_{thJA}	-	-	110	°C/W	
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	-	50		
Maximum Junction-to-Case (Drain)	R_{thJC}	-	-	3.0		

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNIT	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		- 60	-	- V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	- 0.063	- $\text{V}/^\circ\text{C}$	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		- 2.0	-	- 4.0 V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100\text{ nA}$	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = - 60\text{ V}, V_{GS} = 0\text{ V}$		-	-	- 100 μA	
		$V_{DS} = - 48\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	- 500 μA	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = - 10\text{ V}$	$I_D = - 5.3\text{ A}^b$	-	-	0.28 Ω	
Forward Transconductance	g_{fs}	$V_{DS} = - 25\text{ V}, I_D = - 5.3\text{ A}$		2.9	-	- S	
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = - 25\text{ V}, f = 1.0\text{ MHz}$		-	570	- pF	
Output Capacitance	C_{oss}			-	360	-	-
Reverse Transfer Capacitance	C_{rss}			-	65	-	-
Total Gate Charge	Q_g	$V_{GS} = - 10\text{ V}$	$I_D = - 11\text{ A}, V_{DS} = - 48\text{ V},$ see fig. 6 and 13 ^b	-	-	19 nC	
Gate-Source Charge	Q_{gs}			-	-	5.4	-
Gate-Drain Charge	Q_{gd}			-	-	11	-
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = - 30\text{ V}, I_D = - 11\text{ A}, R_g = 18\text{ }\Omega, R_D = 2.5\text{ }\Omega,$ see fig. 10 ^b		-	13	- ns	
Rise Time	t_r			-	68	-	-
Turn-Off Delay Time	$t_{d(off)}$			-	15	-	-
Fall Time	t_f			-	29	-	-
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	- nH	
Internal Source Inductance	L_S			-	7.5	-	-
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 8.8 A	
Pulsed Diode Forward Current ^a	I_{SM}			-	-	- 35	-
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = - 8.8\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	- 6.3 V	
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = - 11\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$		-	100	200 ns	
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.32	0.64	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\text{ }\%$.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

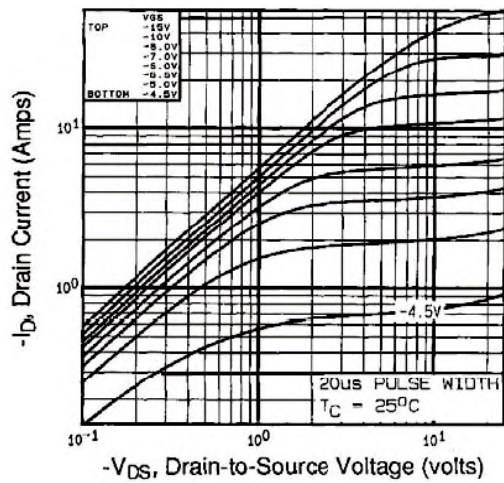


Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$

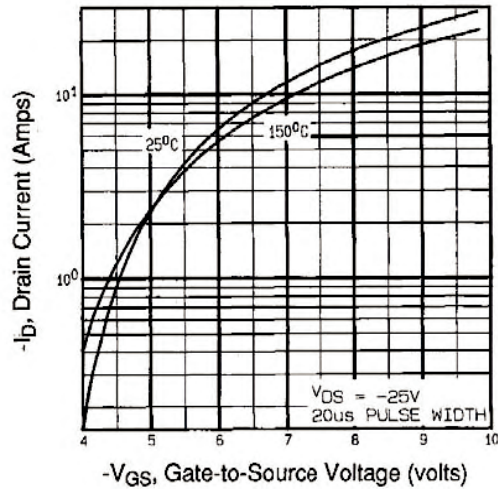


Fig. 3 - Typical Transfer Characteristics

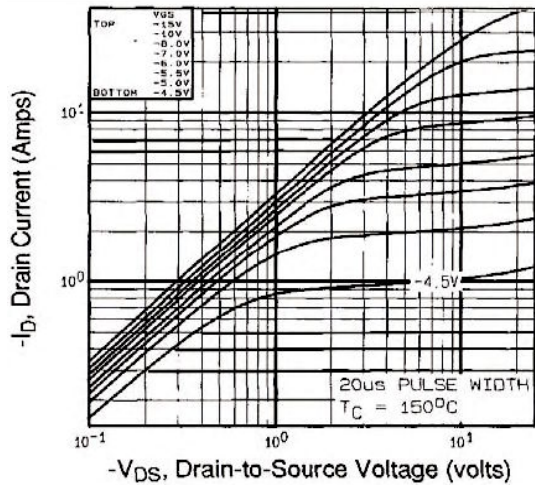


Fig. 2 - Typical Output Characteristics, $T_C = 150\text{ }^\circ\text{C}$

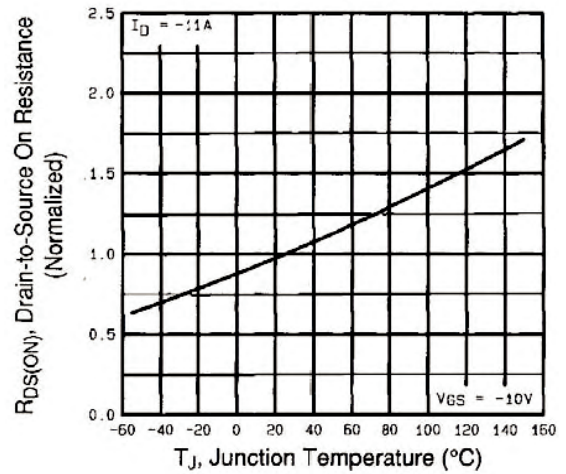


Fig. 4 - Normalized On-Resistance vs. Temperature

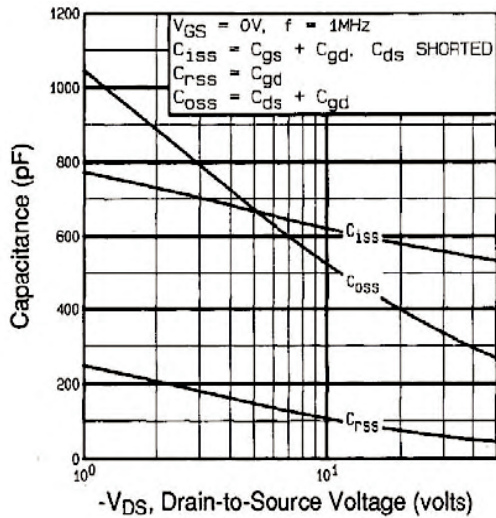


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

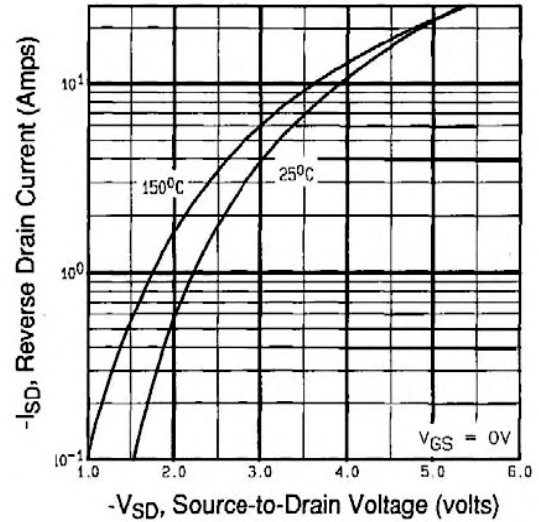


Fig. 7 - Typical Source-Drain Diode Forward Voltage

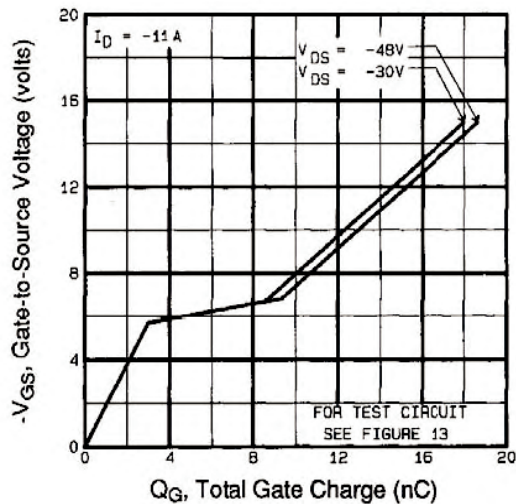


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

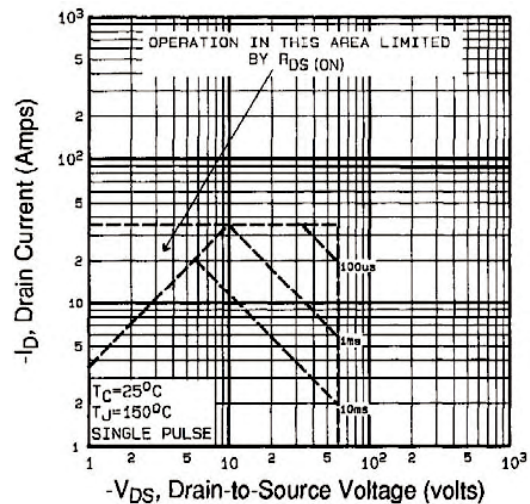


Fig. 8 - Maximum Safe Operating Area

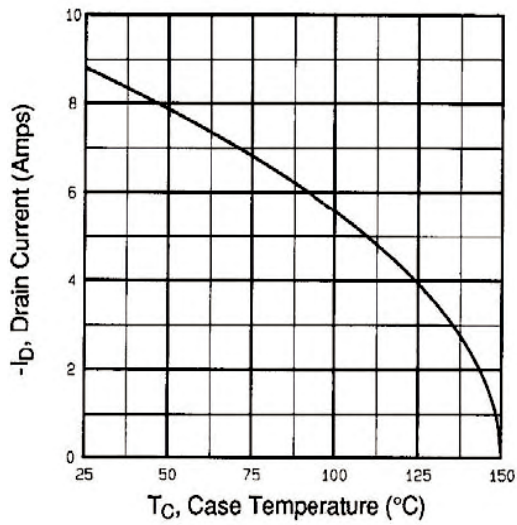


Fig. 9 - Maximum Drain Current vs. Case Temperature

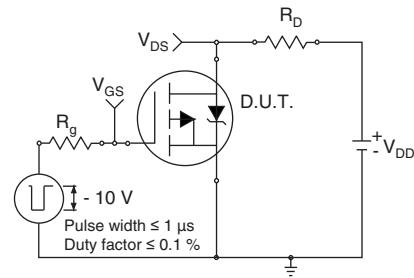


Fig. 10a - Switching Time Test Circuit

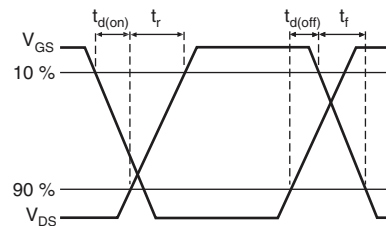


Fig. 10b - Switching Time Waveforms

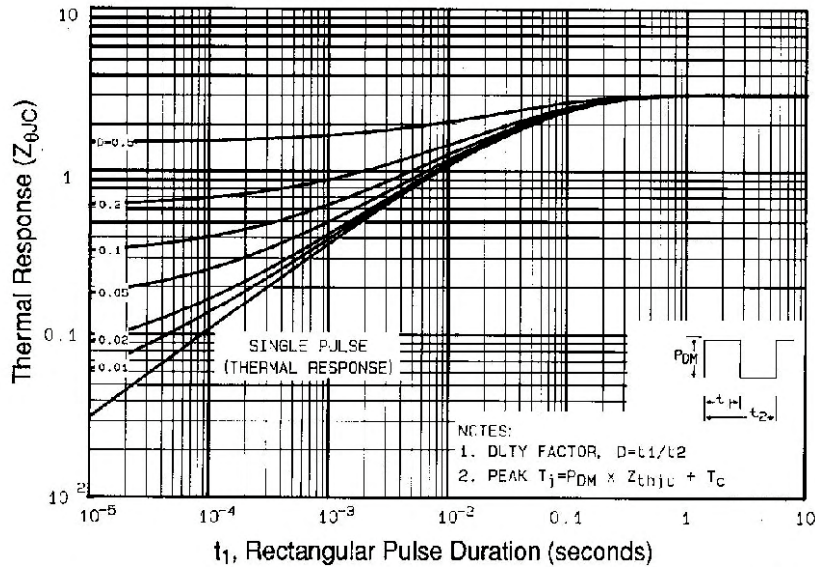


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

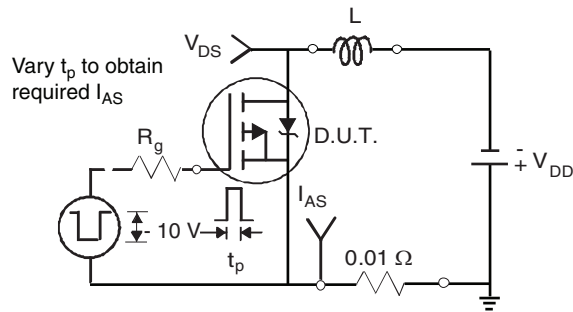


Fig. 12a - Unclamped Inductive Test Circuit

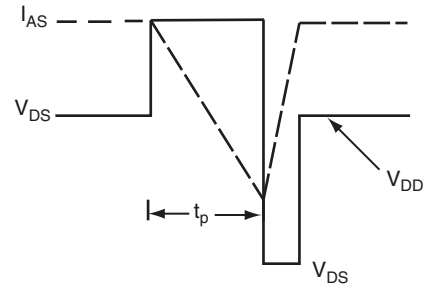


Fig. 12b - Unclamped Inductive Waveforms

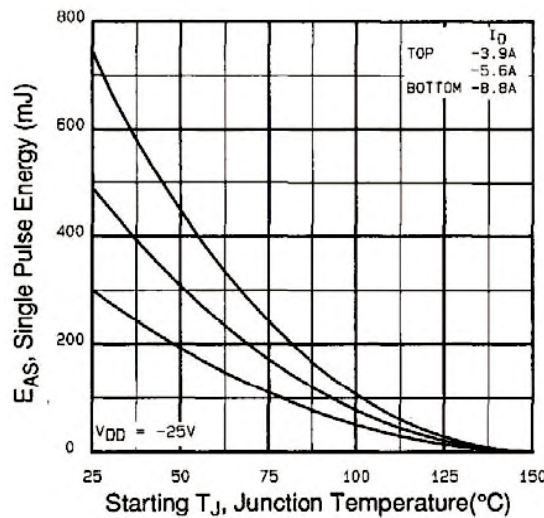


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

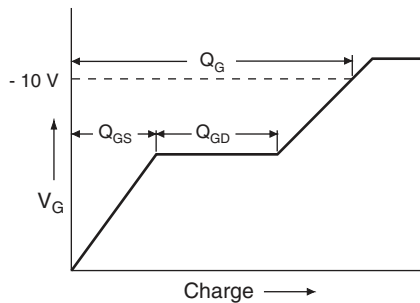


Fig. 13a - Basic Gate Charge Waveform

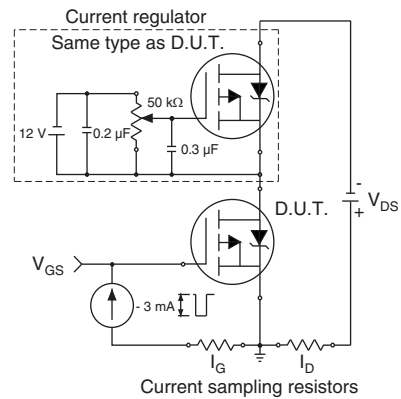
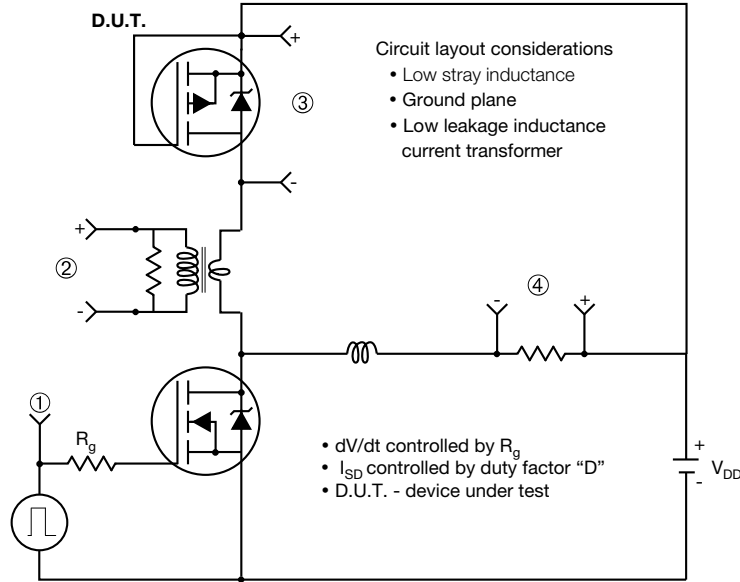


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note
 • Compliment N-Channel of D.U.T. for driver

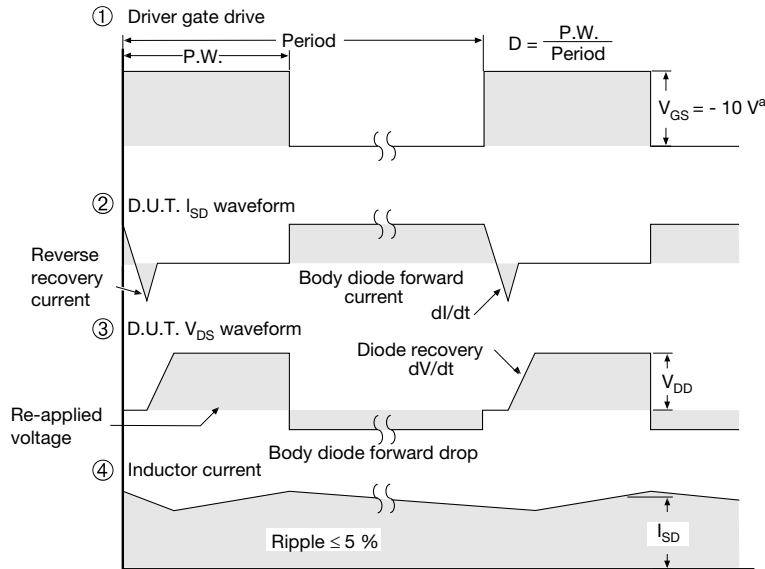


Fig. 14 - For P-Channel

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TO-252AA Case Outline



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.38	0.086	0.094
A1	-	0.127	-	0.005
b	0.64	0.88	0.025	0.035
b2	0.76	1.14	0.030	0.045
b3	4.95	5.46	0.195	0.215
C	0.46	0.61	0.018	0.024
C2	0.46	0.89	0.018	0.035
D	5.97	6.22	0.235	0.245
D1	4.10	-	0.161	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
H	9.40	10.41	0.370	0.410
e	2.28 BSC		0.090 BSC	
e1	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070
L3	0.89	1.27	0.035	0.050
L4	-	1.02	-	0.040
L5	1.01	1.52	0.040	0.060
ECN: T16-0236-Rev. P, 16-May-16 DWG: 5347				

Notes

- Dimension L3 is for reference only.

TO-251AA (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1	0.89	1.14	0.035	0.045
b	0.64	0.89	0.025	0.035
b1	0.65	0.79	0.026	0.031
b2	0.76	1.14	0.030	0.045
b3	0.76	1.04	0.030	0.041
b4	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c1	0.41	0.56	0.016	0.022
c2	0.46	0.86	0.018	0.034
D	5.97	6.22	0.235	0.245

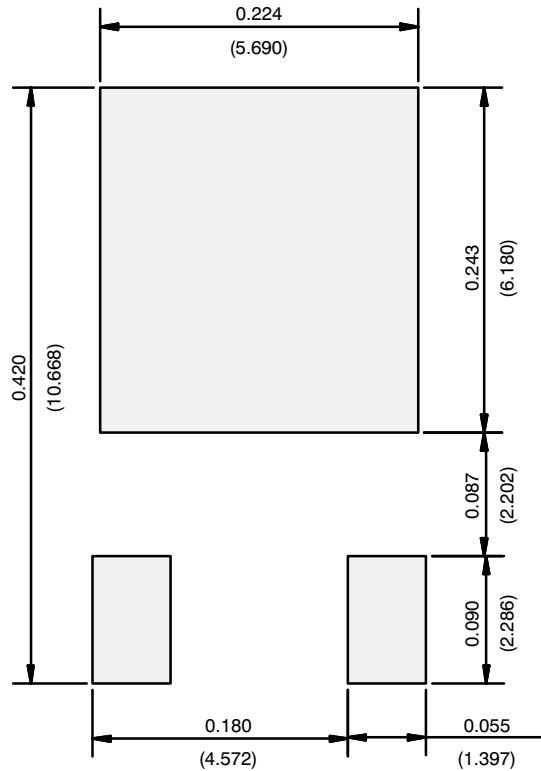
DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	5.21	-	0.205	-
E	6.35	6.73	0.250	0.265
E1	4.32	-	0.170	-
e	2.29 BSC		2.29 BSC	
L	8.89	9.65	0.350	0.380
L1	1.91	2.29	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.14	1.52	0.045	0.060
theta1	0'	15'	0'	15'
theta2	25'	35'	25'	35'

ECN: S-82111-Rev. A, 15-Sep-08
DWG: 5968

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimension are shown in inches and millimeters.
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.13 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
4. Thermal pad contour optional with dimensions b4, L2, E1 and D1.
5. Lead dimension uncontrolled in L3.
6. Dimension b1, b3 and c1 apply to base metal only.
7. Outline conforms to JEDEC outline TO-251AA.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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